FOXCONN®

SPECIFICATIONS

BGA 149SOCKET

BGA Series 450L CPU Socket
Vertical, SMT Type
1.27 mm Pitch
149 Pos.

Mechanical

Durability: *30 Cycles min.*
Socket Retention Force: *65g/Pos. min.*

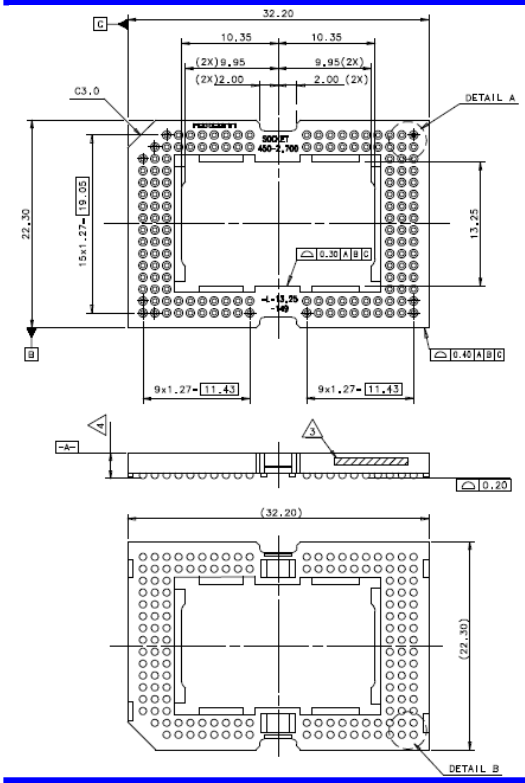
Electrical

Contact Resistance: *35mΩ max.*
Dielectric Withstanding Voltage: *500V*
Insulation Resistance: *800MΩ min.*

Physical

Base: *Thermoplastic, UL 94V-0 rated, Black Color*
Cap: *Thermoplastic, UL 94V-0 rated, Black Color*
Contact: *Copper Alloy*
Plating: *See "ORDERING INFORMATION"*
Operating Temperature: *-55℃ to +110℃*

DRAWING

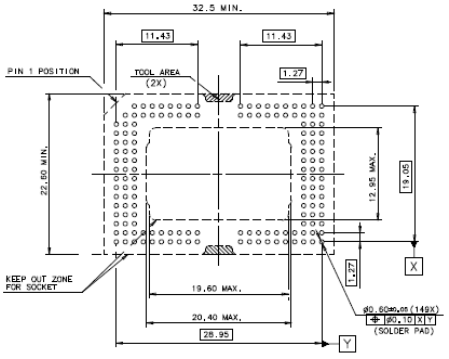


ORDERING INFORMATION

NOTES:

1. PRODUCT NO: P L 1 4 9 2 7 - 1 5 4 2 - 0 1 F

- F=LEAD FREE
- PICK-UP DESIGN 1=PLASTIC PICK-UP CAP
- PACKAGE 0=HARD TRAY
- ACTUATION & BDAY TYPE 1=STANDARD CAM, STANDARD BODY
- BASE COLOR 4=BLACK
- GRID ARRAY TYPE 26=23*26
- CONTACT AREA PLATING 7=GOLD PLATING
- TEMMINNATION TYPE & LENGTH SOLDER BALL TYPE 2=Sn/Ag/Cu LEAD FREE TYPE
- ACTUAL LOADING CONTACTS NO. 149=149 POSITIONS



RECOMMENDED PCB LAYOUT

All specification & dimensions are subject to change, please call your nearest Foxconn sales representative for update information.